

INTERNATIONAL DIRECTORY OF WAFER-BONDING EQUIPMENT AND SERVICES

Company Address ☎ Phone ☒ Fax 🏠 Founded	✕ Category Not Specified Ⓟ Bonding Technologies ◆ Category Not Specified	[web site] ✧ Customer Contact and E-Mail 🌐 Additional Offices <small>Notes: This listing is limited by the amount of space available. For a complete product listing, please contact the vendors or visit their websites. All material listed was supplied by the respective manufacturers. Listings are for current equipment and services for wafer bonding. Some existing wafer fabrication equipment and materials are also used for wafer bonding.</small>
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WAFER-BONDING EQUIPMENT

Applied Microengineering Ltd. 173 Curie Ave. Didcot Oxfordshire OX11 0QG, United Kingdom ☎ +44.1235.833934 🏠 1992	✕ Wafer bonding equipment manufacturer (contact for specific equipment options), high-volume production tools and low-volume R&D tools Ⓟ Anodic bonding, fusion, thermocompression bonding	[aml.co.uk] ✧ Rob Santilli rob@aml.co.uk
EV Group (EVG) E. Thalner GmbH, DI Erich Thalner Strasse 1 A-4780 Schaefering, Austria ☎ +43.7712.5311.0 🏠 1980	✕ Wafer bonding equipment manufacturer (contact for specific equipment options), high-volume production tools and low-volume R&D tools Ⓟ Anodic bonding, fusion, thermocompression bonding ◆ Surface activation, direct wafer bonding, lithography	[evgroup.com] ✧ Dr. Ursula Deinhammer u.deinhammer@evgroup.com ☎ +43.7712.5311.4009
SÜSS MicroTec AG Schleissheimer Str. 90 D-85748 Garching, Munich, Germany ☎ +49.9.89.32770.0 🏠 1949	✕ Wafer bonding equipment manufacturer (contact for specific equipment options), high-volume production tools and low-volume R&D tools Ⓟ Anodic bonding, fusion, thermocompression bonding ◆ Surface activation, direct wafer bonding, lithography	[suss.com] ✧ Jeff Dumas, jdumas@suss.com ☎ 802.244.5181 ext. 222 🌐 SÜSS Micro Tec, 228 Suss Dr., Waterbury Center, VT 05677

WAFER-BONDING SERVICES

APM, Asia Pacific Microsystems Inc. No. 2 R&D Rd. VI, Science-based Industrial Park Hsinchu, Taiwan 300, ROC ☎ +886.3.6661188 ☒ +886.3.6661199 🏠 2001	[apmsinc.com] ✧ Tony Ma, Chief Operating Officer sales.foundry@apmsinc.com
Applied MEMS Inc. (A wholly owned subsidiary of Input/Output Inc.) 12200 Parc Crest Dr., Stafford, TX 77477 ☎ 281.879.2012 🏠 1997	[appliedmems.com] ✧ Howard Goldberg, Business Unit Mgr. hgoldeber@i-o.com ☎ 281.552.3026
MEMSCAP Parc Technologique des Fontaines Bernin, 38926 Crolles Cedex, France ☎ +33.04.76.92.85.00 🏠 1997	[memscap.com] ✧ Ron Wages, Business Unit President and General Manager, Design and Manufacturing Services ron.wages@memscap.com
Walsin Lihwa Corp. 12F, No. 117, Min Sheng E. Road Sec. 3 Taipei, Taiwan ☎ +886.2.2719.2211 🏠 1996	[walsin.com.tw] ✧ Wei-ben Chu wei-ben_chu@walsinc.com ☎ +886.2.2719.2211 ext. 748 ☒ +886.2.2545.2068
Ziptronix Inc. 800 Perimeter Park Dr., Ste. B Morrisville, NC 27560 ☎ 919.459.2400 🏠 2000	[ziptronix.com] ✧ Robert Markunas, VP Market Development r.markunas@ziptronix.com